# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





## DATASHEET

## SMD • REFLECTOR EAPL4040BA0

PRELIMINARY



### Features

- Fluorescence Type
- High Luminous Intensity
- High Efficiency
- Pb-free
- The product itself will remain within RoHS compliant version.

## **Applications**

- OA equipment
- Backlighting of full color LCD
- Automotive equipment
- · Replacement of conventional light bulbs and Fluorescent Lamps

### **Device Selection Guide**

Chip Materials	Emitted Color	Resin Color
InGaN	Blue	Water Clear

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I <sub>FP</sub>	100	mA
Power Dissipation	Pd	110	mW
Electrostatic Discharge(HBM)	ESD	1000	V
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +90	°C
Soldering Temperature	Tsol	Reflow Soldering : $260^{\circ}$ C for 10 sec. Hand Soldering : $350^{\circ}$ C for 3 sec.	

## Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	180		450	mcd	
Viewing Angle	201/2		120		deg	
Peak Wavelength	λр		468		nm	
Dominant Wavelength	λd	464.5		476.5	nm	I <sub>F</sub> =20mA
Spectrum Radiation Bandwidth	Δλ		25		nm	
Forward Voltage	V <sub>F</sub>	2.75		3.95	V	
Reverse Current	I <sub>R</sub>			50	μA	VR=5V

#### Note:

1. Tolerance of Luminous Intensity: ±11%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V

## **Bin Range of Luminous Intensity**

Bin Code	Min.	Max.	Unit	Conduction	
S1	180	225			
S2	225	285	mod	I <sub>F</sub> =20mA	
T1	285	360	- mcd	IF=2011A	
T2	360	450			

Note:

Tolerance of Luminous Intensity: ±11%

## **Bin Range of Dominant Wavelength**

Groups	Bin	Min	Max	Unit	Condition	
A	A9	464.5	467.5			
	A10	467.5	470.5			
	A11	470.5	473.5	nm	I <sub>F</sub> =20mA	
	A12	473.5	476.5			

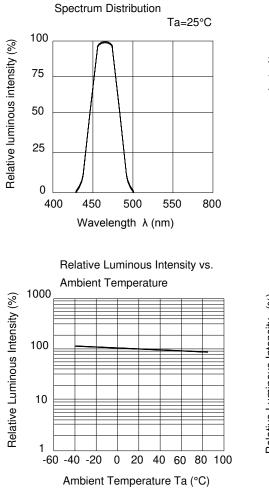
Note: Tolerance of Dominant Wavelength: ±1nm

## **Bin Range of Forward Voltage**

Groups	Bin	Min	Мах	Unit	Condition	
М	5	2.75	3.05			
	6	3.05	3.35	volt	L 00m A	
	7	3.35	3.65	VOIL	I <sub>F</sub> =20mA	
	8	3.65	3.95			

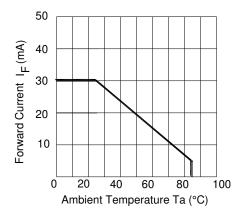
Note: Tolerance of Forward Voltage: ±0.1V

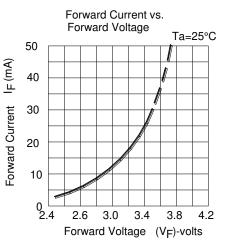
#### DATASHEET SMD • REFLECTOR EAPL4040BA0



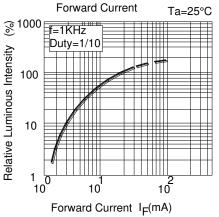
## **Typical Electro-Optical Characteristics Curves**

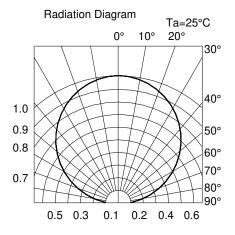




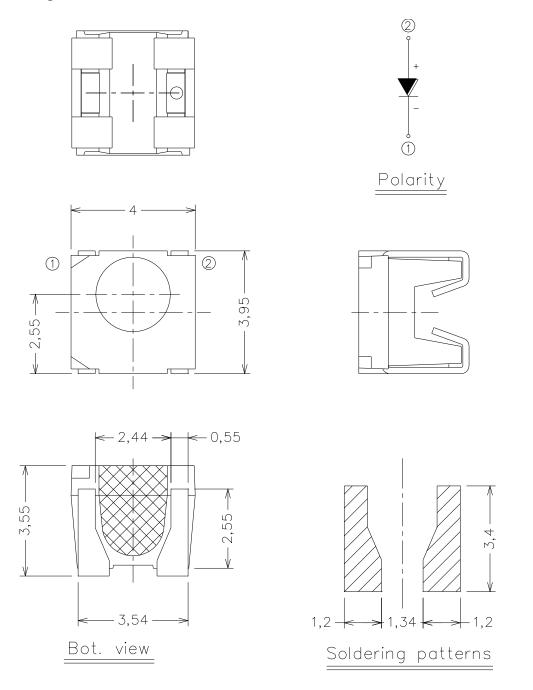


Relative Luminous Intensity vs





## **Package Dimension**



Note: Tolerances unless mentioned ±0.1mm. Unit = mm



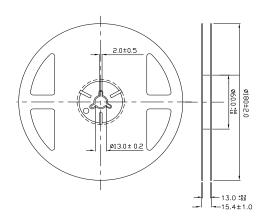
### **Moisture Resistant Packing Materials**

#### Label Explanation

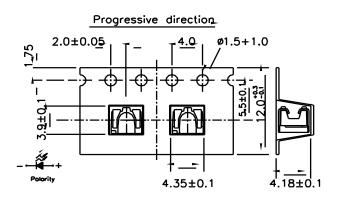


CAT: Luminous Intensity Rank HUE: Dom. Wavelength Rank REF: Forward Voltage Rank

#### **Reel Dimensions**

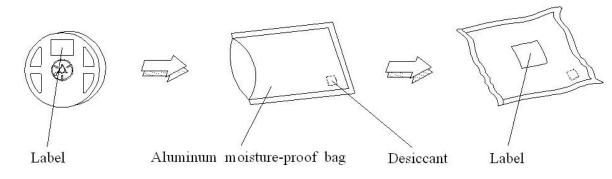


#### Carrier Tape Dimensions: Loaded Quantity 500 pcs Per Reel



Note: Tolerances unless mentioned  $\pm 0.1$  mm. Unit = mm

#### **Moisture Resistant Packing Process**



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

#### **Reliability Test Items and Conditions**

The reliability of products shall be satisfied with items listed below. Confidence level : 90% LTPD : 10%

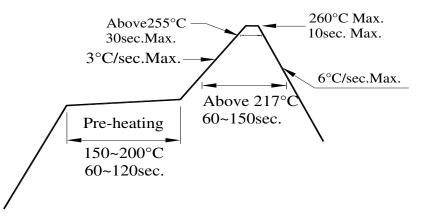
No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 pcs.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫5 min L : -40℃ 15min	300 Cycles	22 pcs.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 pcs.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 pcs.	0/1
5	Low Temperature Storage	<b>Temp.</b> : -40℃	1000 Hrs.	22 pcs.	0/1
6	DC Operating Life	l <sub>F</sub> = 20 mA	1000 Hrs.	22 pcs.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 pcs.	0/1

#### Precautions for Use 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at  $30^{\circ}$ C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 72 hours under 30  $^\circ\!C$  or less and 60% RH or less.
- If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5℃ for 24 hours.
- 3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

